

ISO 1043

ISO 11469

ISO 11359-1/-2

ISO 11359-1/-2

ISO 11359-1/-2

ISO 11359-1/-2

ISO 11359-1/-2

ISO 11359-1/-2

**UL 746B** 

**UL 746B** 

## Zytel® HTNFR52G30NH NC010

#### HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimise performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTNFR52G30NH NC010 is a 30% glass reinforced, flame retardant high performance polyamide resin. It is also a PPA resin and it uses a non-halogenated flame retardant.

PA6T/66-GF30FR(40)

>PA6T/66-GF30FR(40)<

## Product information Resin Identification

Part Marking Code

Part Marking Code ISO designation	>PPA-GF30FR< ISO 16396-PA6T	7/66,GF30 FR(40	SAE J1344 0),M1F1GNR,S10-100
Rheological properties	dry/cond.		
Moulding shrinkage, parallel Moulding shrinkage, normal	0.3/- 1.1/-	% %	ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties	dry/cond.		
Tensile modulus Tensile stress at break, 5mm/min Tensile strain at break, 5mm/min Flexural modulus Flexural strength Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Poisson's ratio	10500/10500 150/130 2.2/2 9000/10000 230/200 45/40 40/35 8/7 7/7 0.34/0.34	MPa MPa % MPa MPa kJ/m² kJ/m² kJ/m²	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 178 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA
Thermal properties	dry/cond.		
Melting temperature, 10°C/min Melting temperature, first heat Glass transition temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Ball pressure test	310/* 310/* 90/45 283/* 290/-	°C °C °C °C	ISO 11357-1/-3 ISO 11357-1/-3 ISO 11357-1/-3 ISO 75-1/-2 IEC 60695-10-2

Printed: 2025-03-27 Page: 1 of 9

20/\*

20/\*

20/\*

60/\*

60/\*

100/\*

140

140

E-6/K

E-6/K

E-6/K

E-6/K

E-6/K

E-6/K

°C

°C

Revised: 2025-01-28 Source: Celanese Materials Database

Coeff. of linear therm. expansion, parallel, -40-23°C

Coeff. of linear therm. expansion, parallel, 55-160°C

Coeff. of linear therm. expansion, normal, -40-23°C

Coeff. of linear therm. expansion, normal, 55-160°C

Coefficient of linear thermal expansion (CLTE),

Coefficient of linear thermal expansion

(CLTE), parallel

RTI, electrical, 0.4mm

RTI, electrical, 0.75mm

normal



## HIGH PERFORMANCE POLYAMIDE RESIN

RTI, electrical, 1.5mm RTI, electrical, 3.0mm RTI, impact, 0.75mm RTI, impact, 1.5mm RTI, impact, 3.0mm RTI, strength, 0.75mm RTI, strength, 1.5mm RTI, strength, 3.0mm	140 140 115 115 120 125 125/*	, , , , , , , ,	UL 746B UL 746B UL 746B UL 746B UL 746B UL 746B UL 746B UL 746B
Flammability	dry/cond.		
Burning Behav. at 1.5mm nom. thickn. Thickness tested UL recognition Burning Behav. at thickness h Thickness tested UL recognition Oxygen index Glow Wire Flammability Index, 0.75mm Glow Wire Flammability Index, 3.0mm Glow Wire Ignition Temperature, 0.75mm Glow Wire Ignition Temperature, 0.4mm Glow Wire Ignition Temperature, 3.0mm	V-0/* 1.5/* yes/* V-0/* 0.4/* yes/* 37/* 960/- 960/- 725/- 700/- 800/-	class mm class mm % °C °C °C °C	IEC 60695-11-10 IEC 60695-11-10 UL 94 IEC 60695-11-10 IEC 60695-11-10 UL 94 ISO 4589-1/-2 IEC 60695-2-12 IEC 60695-2-12 IEC 60695-2-13 IEC 60695-2-12 IEC 60695-2-13
FMVSS Class	DNI		ISO 3795 (FMVSS 302)
Relative permittivity, 100Hz Relative permittivity, 1MHz Dissipation factor, 100Hz Dissipation factor, 1MHz Volume resistivity Surface resistivity Electric strength Comparative tracking index Electric Strength, Short Time, 2mm Dielectric Constant, 1 GHz Dielectric Constant, 23°C, 10 GHz  Dissipation Factor, 1 GHz Dissipation Factor, 23°C, 10 GHz	dry/cond.  4.1/- 3.9/- 65/- 120/- >1E13/5E11  */>1E15 39/- 600/- 26/- 3.7/- 3.8/-  110/- 100/-	E-4 E-4 Ohm.m Ohm kV/mm kV/mm	IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-3-1 IEC 62631-3-2 IEC 60243-1 IEC 60112 IEC 60243-1 ASTM D 2520 B ASTM D 2520 B / IPC- TM-650 ASTM D 2520 B / IPC- TM-650 TM-650
Physical/Other properties Humidity absorption, 2mm Water absorption, 2mm Density	dry/cond. 1.6/* 3.9/* 1440/-	% % kg/m³	Sim. to ISO 62 Sim. to ISO 62 ISO 1183

Printed: 2025-03-27 Page: 2 of 9



### HIGH PERFORMANCE POLYAMIDE RESIN

#### **VDA Properties**

Odour 3.5 class VDA 270

#### Injection

Drying Recommended	yes	
Drying Temperature	100 °C	;
Drying Time, Dehumidified Dryer	6-8 h	
Processing Moisture Content	≤0.1 %	
Melt Temperature Optimum	325 °C	;
Min. melt temperature	320 °C	;
Max. melt temperature	330 °C	;
Mold Temperature Optimum	100 °C	;
Min. mould temperature	90 °C	;
Max. mould temperature	130 °C	;
Ejection temperature	259 °C	;

#### Characteristics

Processing Injection Moulding

Delivery form Pellets

Additives Release agent, Flame retardant, Non-halogenated/Red phosphorous free flame

retardant

Special characteristics Flame retardant, Lead-free soldering resistant

Additional information

Injection molding For molding machine components, use corrosion resistant and wear resistant

steel. For details please contact our representative. Limit the residence time of  $% \left\{ 1\right\} =\left\{ 1\right\} =$ 

the resin in the machine. Use proper protective equipment and adequate

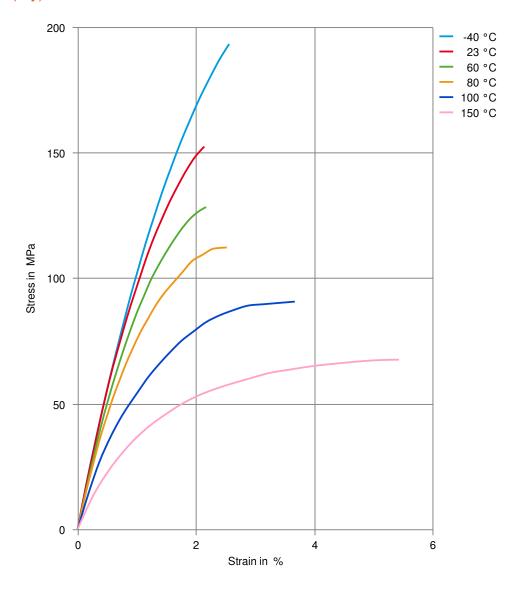
ventilation.

Printed: 2025-03-27 Page: 3 of 9



## HIGH PERFORMANCE POLYAMIDE RESIN

### Stress-strain (dry)

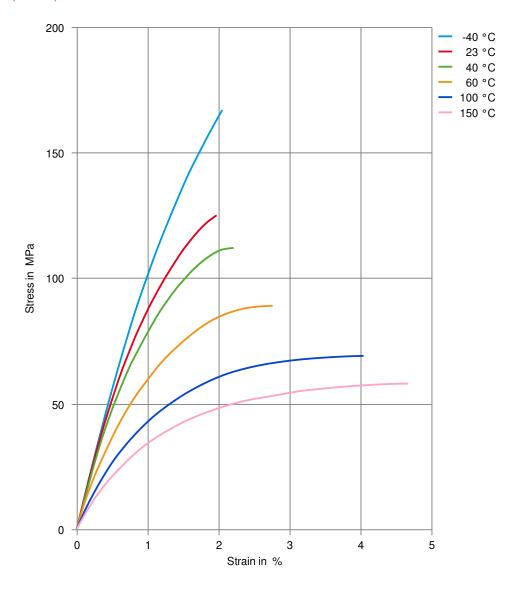


Printed: 2025-03-27 Page: 4 of 9



## HIGH PERFORMANCE POLYAMIDE RESIN

### Stress-strain (cond.)

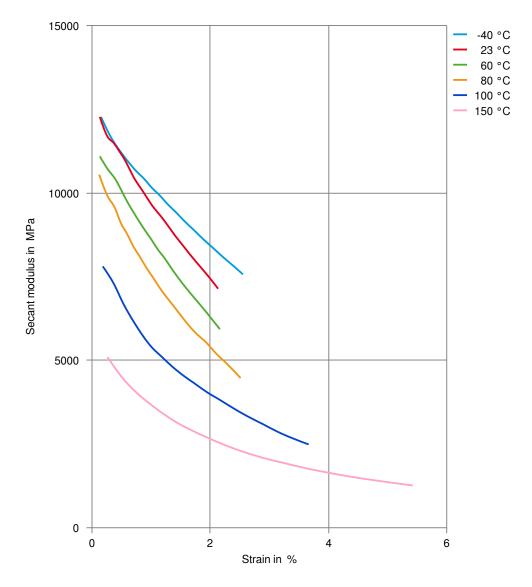


Printed: 2025-03-27 Page: 5 of 9



## HIGH PERFORMANCE POLYAMIDE RESIN

### Secant modulus-strain (dry)

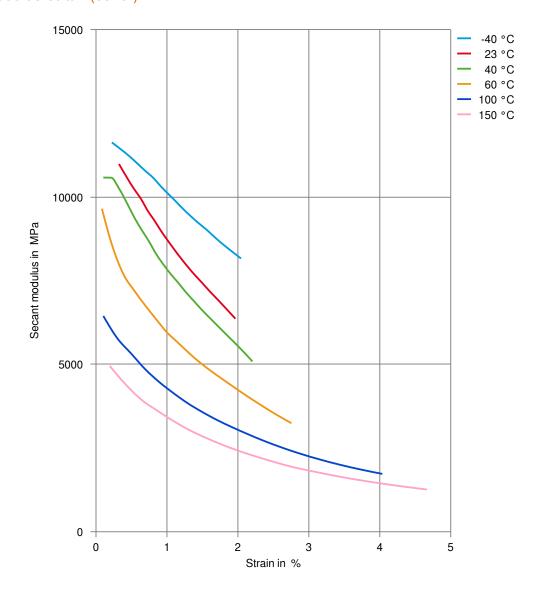


Printed: 2025-03-27 Page: 6 of 9



## HIGH PERFORMANCE POLYAMIDE RESIN

Secant modulus-strain (cond.)

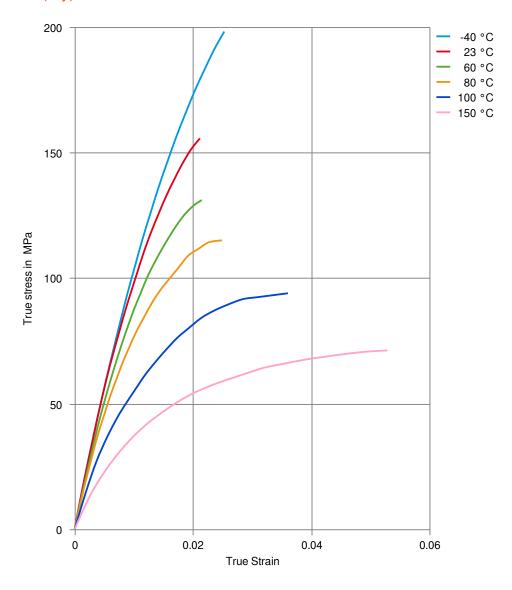


Printed: 2025-03-27 Page: 7 of 9



## HIGH PERFORMANCE POLYAMIDE RESIN

### True stress-strain (dry)

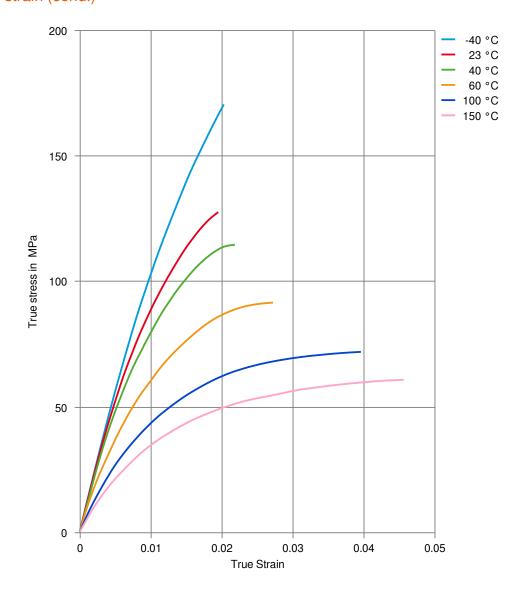


Printed: 2025-03-27 Page: 8 of 9



#### HIGH PERFORMANCE POLYAMIDE RESIN

#### True stress-strain (cond.)



Printed: 2025-03-27 Page: 9 of 9

Revised: 2025-01-28 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any e

© 2025 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC. KEPITAL is a registered trademark of Korea Engineering Plastics Company, Ltd.